

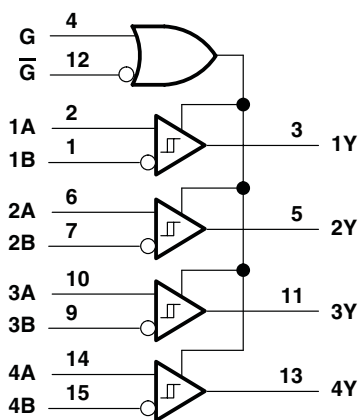
**AM26LS32AC, AM26LS32AI, AM26LS33AC
AM26LS32AM, AM26LS33AM
QUADRUPLE DIFFERENTIAL LINE RECEIVERS**

SLLS115E—OCTOBER 1980—REVISED OCTOBER 2007

**FUNCTION TABLE
Each Receiver**

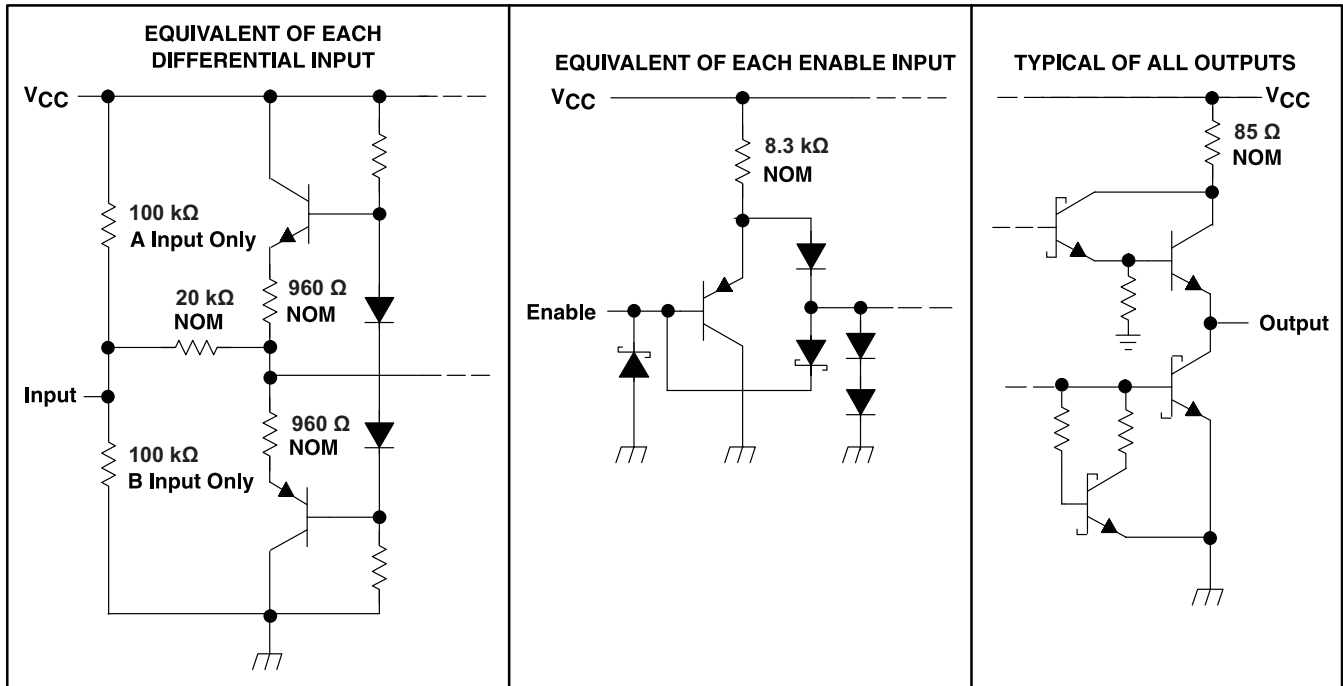
DIFFERENTIAL A-B	ENABLES		OUTPUT Y
	G	\bar{G}	
$V_{ID} \geq V_{IT+}$	H	X	H
	X	L	H
$V_{IT-} \leq V_{ID} \leq V_{IT+}$	H	X	?
	X	L	?
$V_{ID} \leq V_{IT-}$	H	X	L
	X	L	L
X	L	H	Z
Open	H	X	H
	X	L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers are for D, N, NS, or PW packages only.

SCHEMATICS OF INPUTS AND OUTPUTS



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage ⁽²⁾		7	V
V_I	Input voltage	Any differential input		±25
		Other inputs		7
V_{ID}	Differential input voltage ⁽³⁾		±25	V
Continuous total power dissipation		See Dissipation Ratings Table		
θ_{JA}	Package thermal impedance ⁽⁴⁾	D package		73
		N package		67
		NS package		64
		PW package		108
T_C	Case temperature for 60 seconds	FK package		260
	Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	D or N package		260
	Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J package		300
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground terminal.
- (3) Differential voltage values are at the noninverting (A) input terminals with respect to the inverting (B) input terminals.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

AM26LS32AC, AM26LS32AI, AM26LS33AC AM26LS32AM, AM26LS33AM QUADRUPLE DIFFERENTIAL LINE RECEIVERS



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DISSIPATION RATINGS

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATION FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
FK	1375 mW	11.0 mW/°C	880 mW	275 mW
J	1375 mW	11.0 mW/°C	880 mW	275 mW

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT		
V_{CC}	Supply voltage	AM26LS32AC, AM26LS32AI, AM26LS33AC		4.75	5	5.25	V
		AM26LS32AM, AM26LS33AM		4.5	5	5.5	
V_{IH}	High-level input voltage	2				V	
V_{IL}	Low-level input voltage				0.8	V	
V_{IC}	Common-mode input voltage	AM26LS32A		± 7		V	
		AM26LS33A		± 15			
I_{OH}	High-level output current				-440	μA	
I_{OL}	Low-level output current				8	mA	
T_A	Operating free-air temperature	AM26LS32AC, AM26LS33AC		0	70	°C	
		AM26LS32AI		-40	85		
		AM26LS32AM, AM26LS33AM		-55	125		

ELECTRICAL CHARACTERISTICS

over recommended ranges of V_{CC} , V_{IC} , and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	$V_O = V_{OHmin}$, $I_{OH} = -440 \mu\text{A}$	AM26LS32A			0.2	V
			AM26LS33A			0.5	
V_{IT-}	Negative-going input threshold voltage	$V_O = 0.45 \text{ V}$, $I_{OL} = 8 \text{ mA}$	AM26LS32A			-0.2 ⁽²⁾	V
			AM26LS33A			-0.5 ⁽²⁾	
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)			50			mV
V_{IK}	Enable-input clamp voltage	$V_{CC} = \text{MIN}$,	$I_I = -18 \text{ mA}$			-1.5	V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$, $V_{ID} = 1 \text{ V}$, $V_{I(G)} = 0.8 \text{ V}$, $I_{OH} = -440 \mu\text{A}$	AM26LS32AC, AM26LS33AC	2.7			V
			AM26LS32AM, AM26LS32AI, AM26LS33AM	2.5			
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$, $V_{ID} = -1 \text{ V}$, $V_{I(G)} = 0.8 \text{ V}$	$I_{OL} = 4 \text{ mA}$			0.4	V
			$I_{OL} = 8 \text{ mA}$			0.45	
I_{OZ}	Off-state (high-impedance state) output current	$V_{CC} = \text{MAX}$	$V_O = 2.4 \text{ V}$			20	μA
			$V_O = 0.4 \text{ V}$			-20	
I_I	Line input current	$V_I = 15 \text{ V}$,	Other input at -10 V to 15 V		1.2		mA
		$V_I = -15 \text{ V}$,	Other input at -15 V to 10 V		-1.7		
$I_{I(EN)}$	Enable input current	$V_I = 5.5 \text{ V}$			100		μA
I_H	High-level enable current	$V_I = 2.7 \text{ V}$			20		μA

(1) All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$, and $V_{IC} = 0$.

(2) The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.

ELECTRICAL CHARACTERISTICS (continued)

 over recommended ranges of V_{CC} , V_{IC} , and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
I_L	Low-level enable current	$V_I = 0.4\text{ V}$			–0.36	mA
r_i	Input resistance	$V_{IC} = -15\text{ V to }15\text{ V}$, One input to ac ground	12	15		k Ω
I_{OS}	Short-circuit output current ⁽³⁾	$V_{CC} = \text{MAX}$	–15		–85	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$, All outputs disabled		52	70	mA

(3) Not more than one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second.

SWITCHING CHARACTERISTICS
 $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

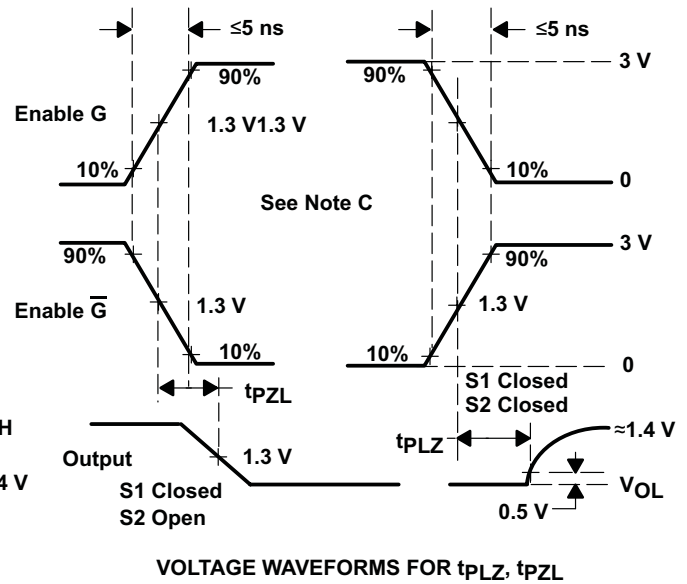
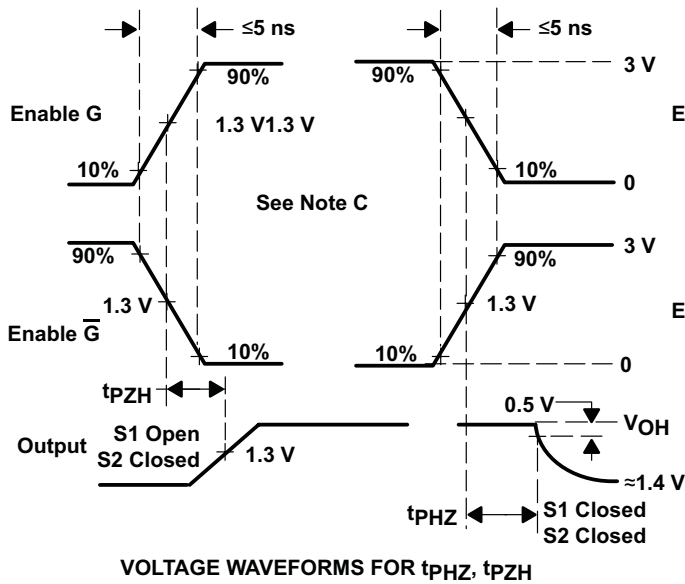
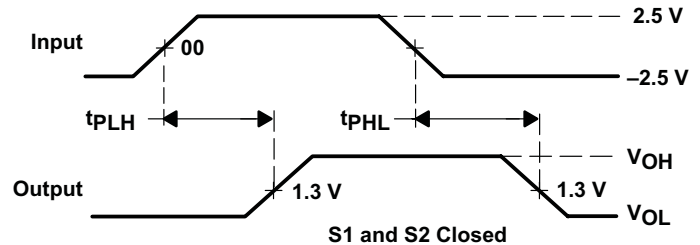
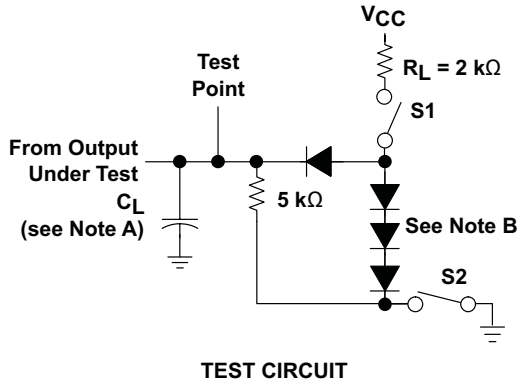
PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	$C_L = 15\text{ pF}$, See Figure 1		20	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output			22	35	
t_{PZH}	Output enable time to high level	$C_L = 15\text{ pF}$, See Figure 1		17	22	ns
t_{PZL}	Output enable time to low level			20	25	
t_{PHZ}	Output disable time from high level	$C_L = 15\text{ pF}$, See Figure 1		21	30	ns
t_{PLZ}	Output disable time from low level			30	40	

 (1) All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, and $V_{IC} = 0$.

AM26LS32AC, AM26LS32AI, AM26LS33AC
 AM26LS32AM, AM26LS33AM
 QUADRUPLE DIFFERENTIAL LINE RECEIVERS

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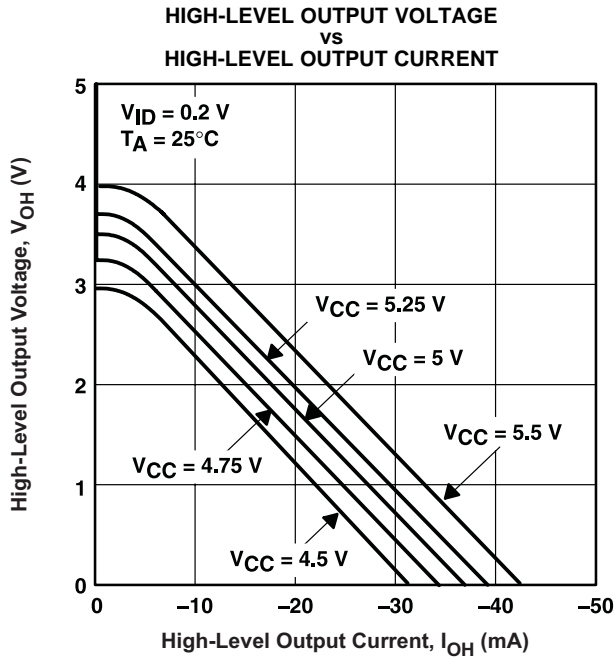
PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. All diodes are 1N3064 or equivalent.
 C. Enable G is tested with \bar{G} high; \bar{G} is tested with G low.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS



† $V_{CC} = 5.5 \text{ V}$ and $V_{CC} = 4.5 \text{ V}$ applies to M-suffix devices only.

Figure 2.

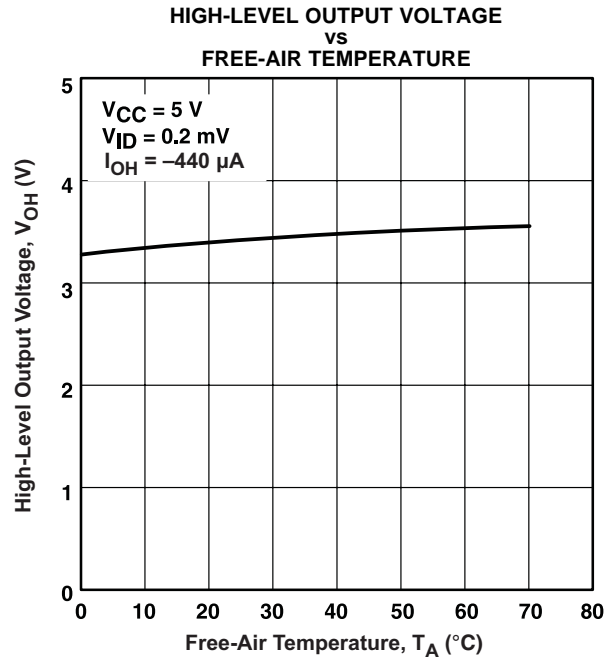


Figure 3.

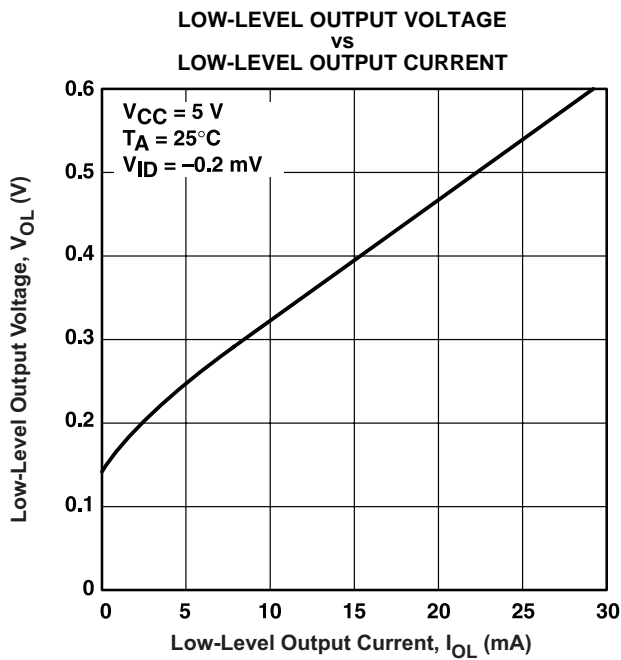


Figure 4.

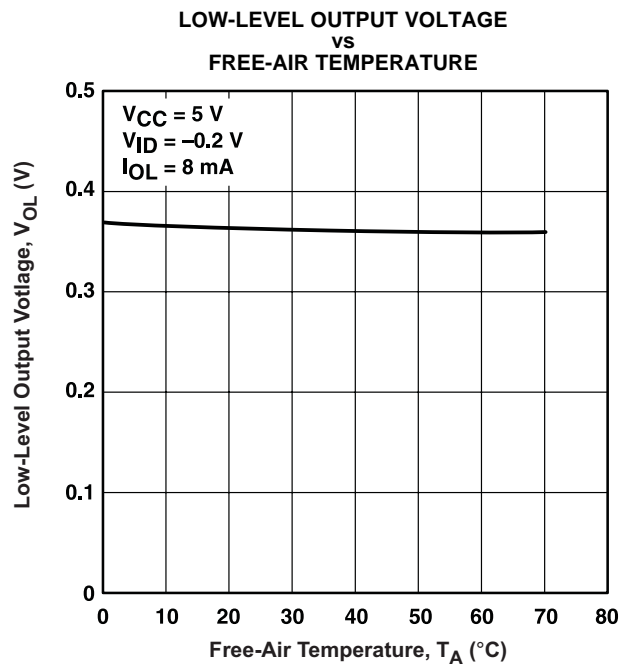


Figure 5.

TYPICAL CHARACTERISTICS (continued)

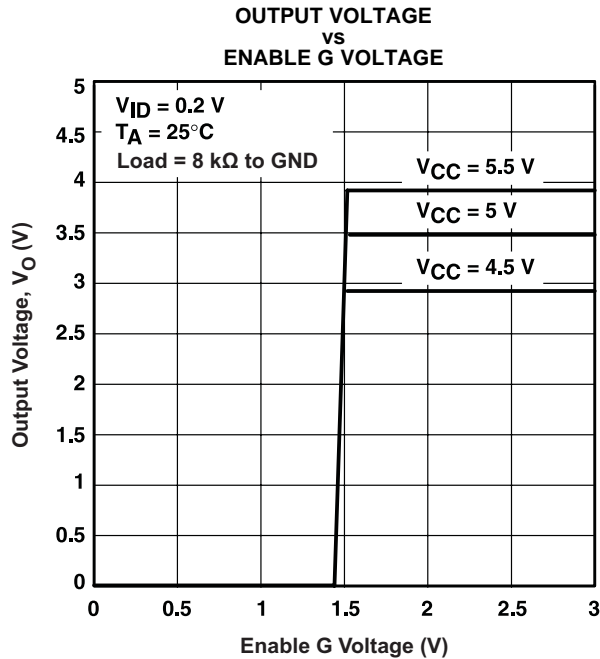


Figure 6.

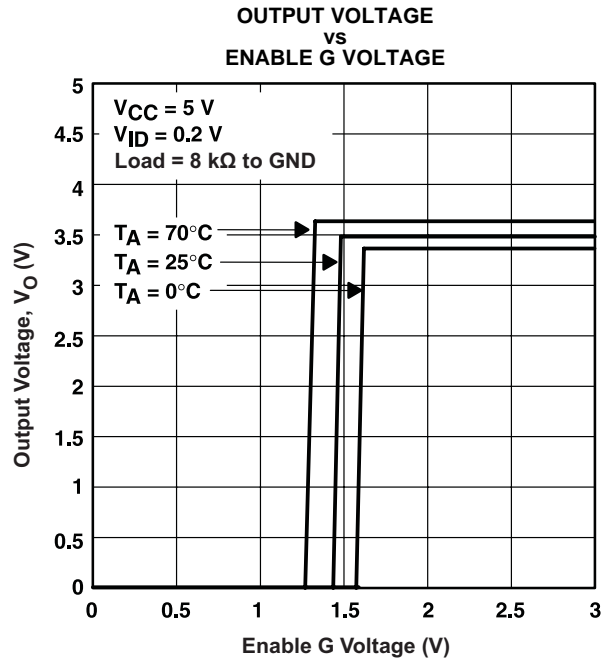


Figure 7.

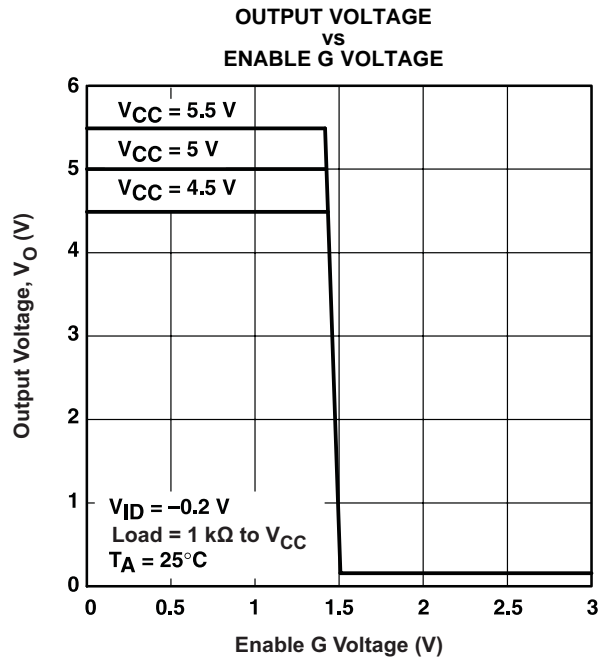


Figure 8.

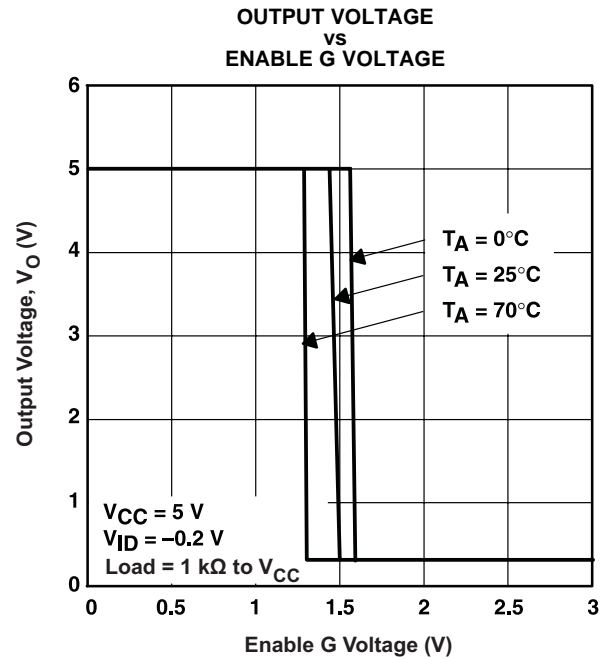


Figure 9.

TYPICAL CHARACTERISTICS (continued)

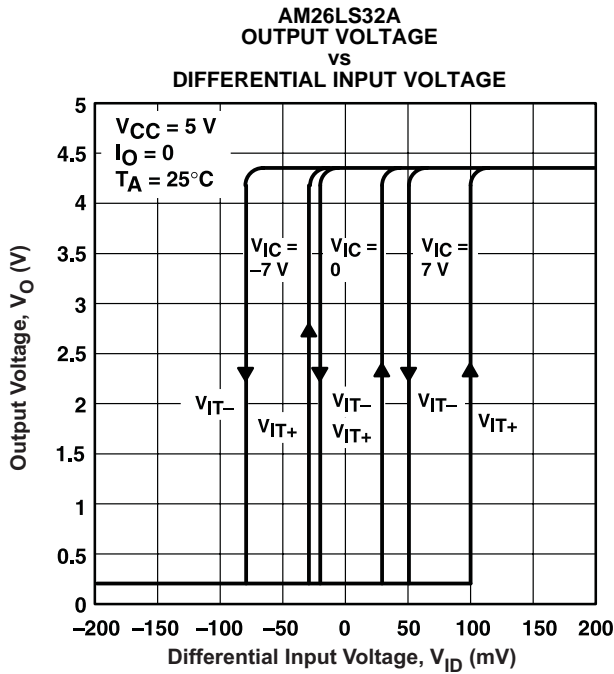


Figure 10.

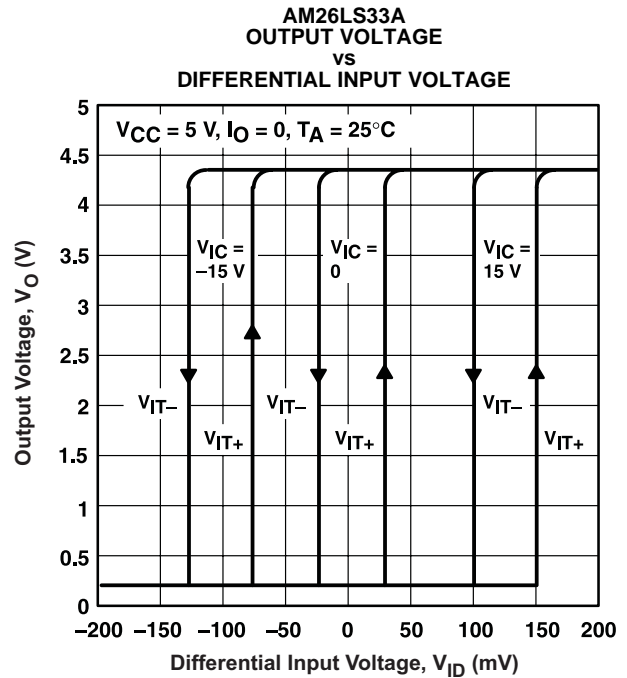
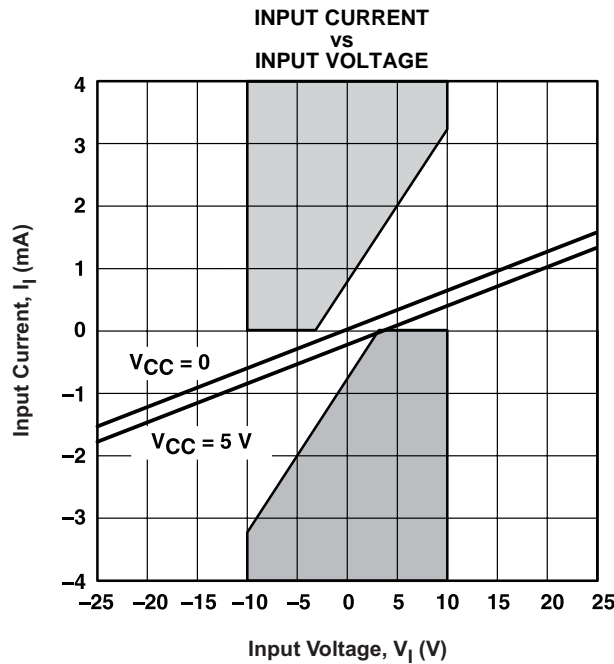


Figure 11.



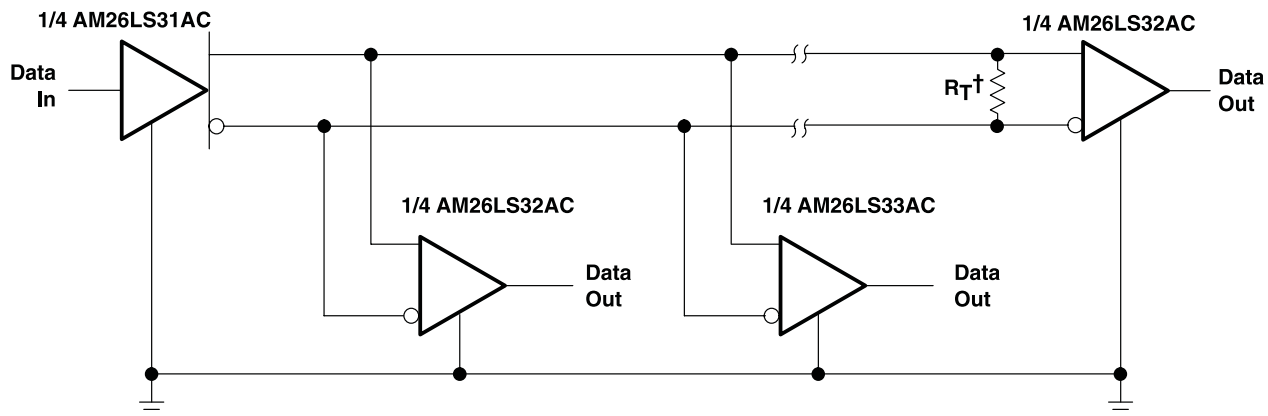
The unshaded area shows requirements of paragraph 4.2.1 of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B.

Figure 12.

AM26LS32AC, AM26LS32AI, AM26LS33AC
AM26LS32AM, AM26LS33AM
QUADRUPLE DIFFERENTIAL LINE RECEIVERS

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APPLICATION INFORMATION



† R_T equals the characteristic impedance of the line.

Figure 13. Circuit with Multiple Receivers

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-7802003M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-7802003MEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-7802003MFA	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-7802004M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-7802004MEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-7802004MFA	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS32ACD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS32ACNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS32ACNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32ACPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AIDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AIDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AIDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
AM26LS32AIDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS32AIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS32AINE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS32AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
AM26LS32AMJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS32AMJB	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS32AMWB	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS33ACD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS33ACN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS33ACNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS33AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
AM26LS33AMJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS33AMJB	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
AM26LS33AMWB	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

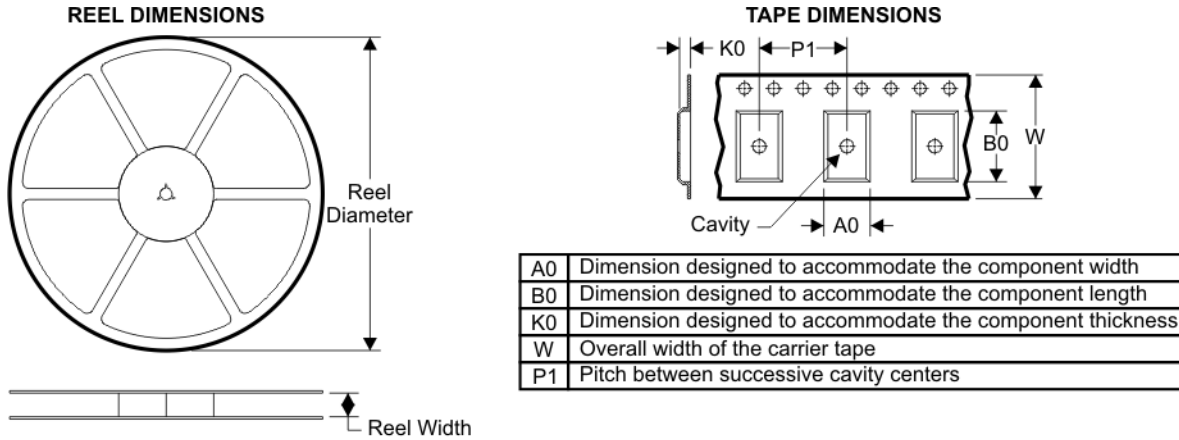
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

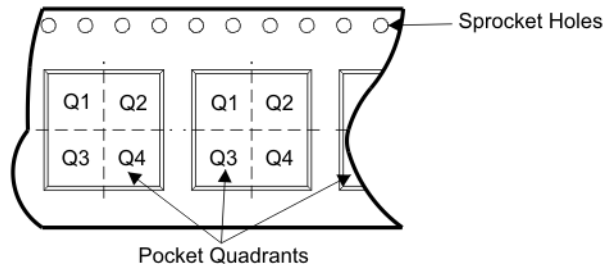
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TAPE AND REEL BOX INFORMATION

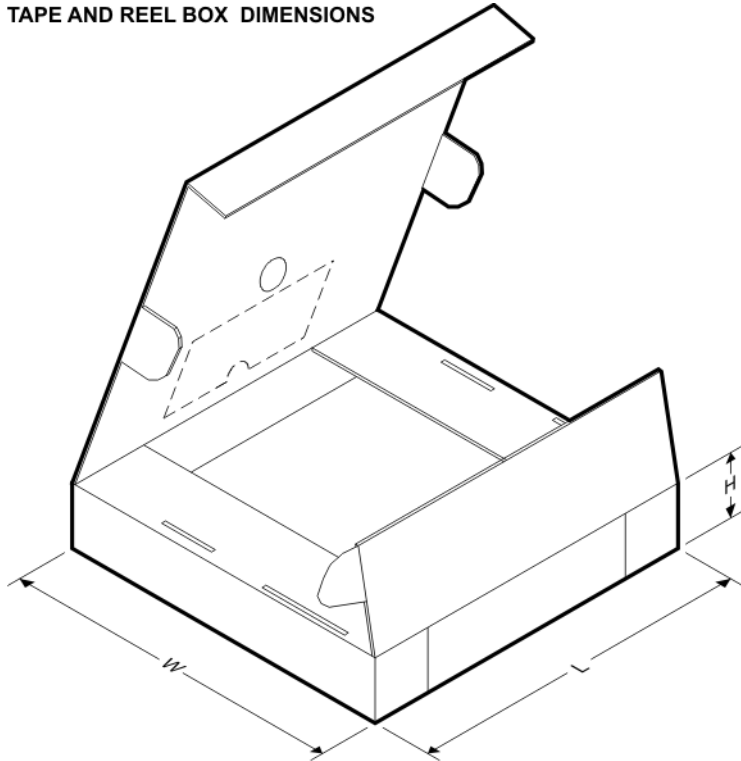


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26LS32ACDR	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1
AM26LS32ACDR	D	16	SITE 41	330	16	6.5	10.3	2.1	8	16	Q1
AM26LS32ACNSR	NS	16	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
AM26LS32ACPWR	PW	16	SITE 41	330	12	7.0	5.6	1.6	8	12	Q1
AM26LS32AIDR	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1
AM26LS33ACDR	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1

TAPE AND REEL BOX DIMENSIONS

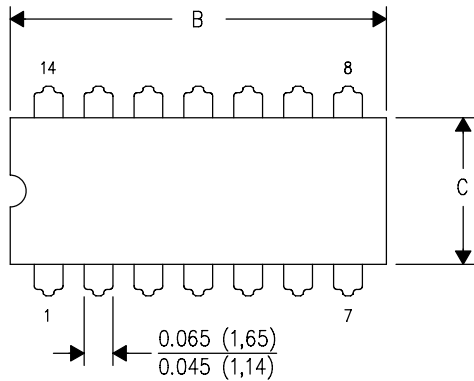


Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
AM26LS32ACDR	D	16	SITE 27	342.9	336.6	28.58
AM26LS32ACDR	D	16	SITE 41	346.0	346.0	33.0
AM26LS32ACNSR	NS	16	SITE 41	346.0	346.0	33.0
AM26LS32ACPWR	PW	16	SITE 41	346.0	346.0	29.0
AM26LS32AIDR	D	16	SITE 27	342.9	336.6	28.58
AM26LS33ACDR	D	16	SITE 27	342.9	336.6	28.58

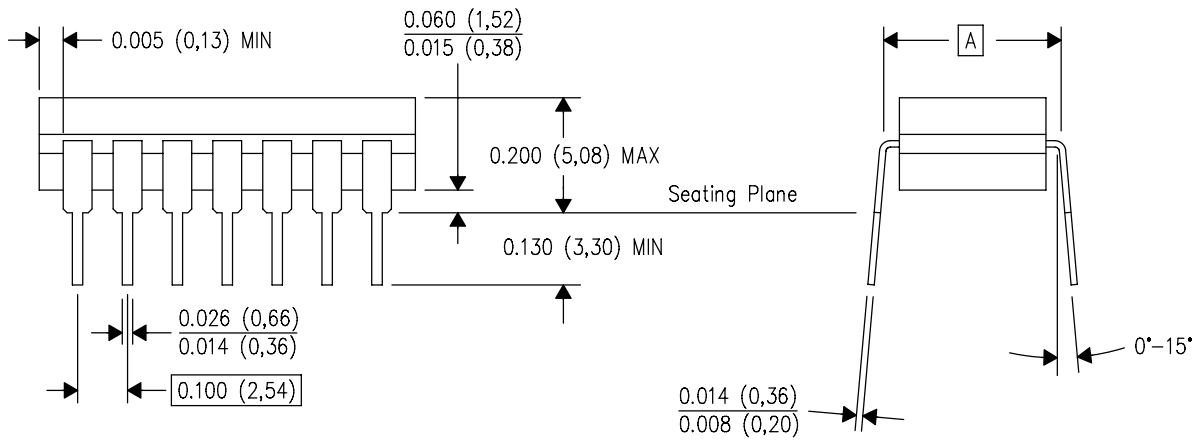
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



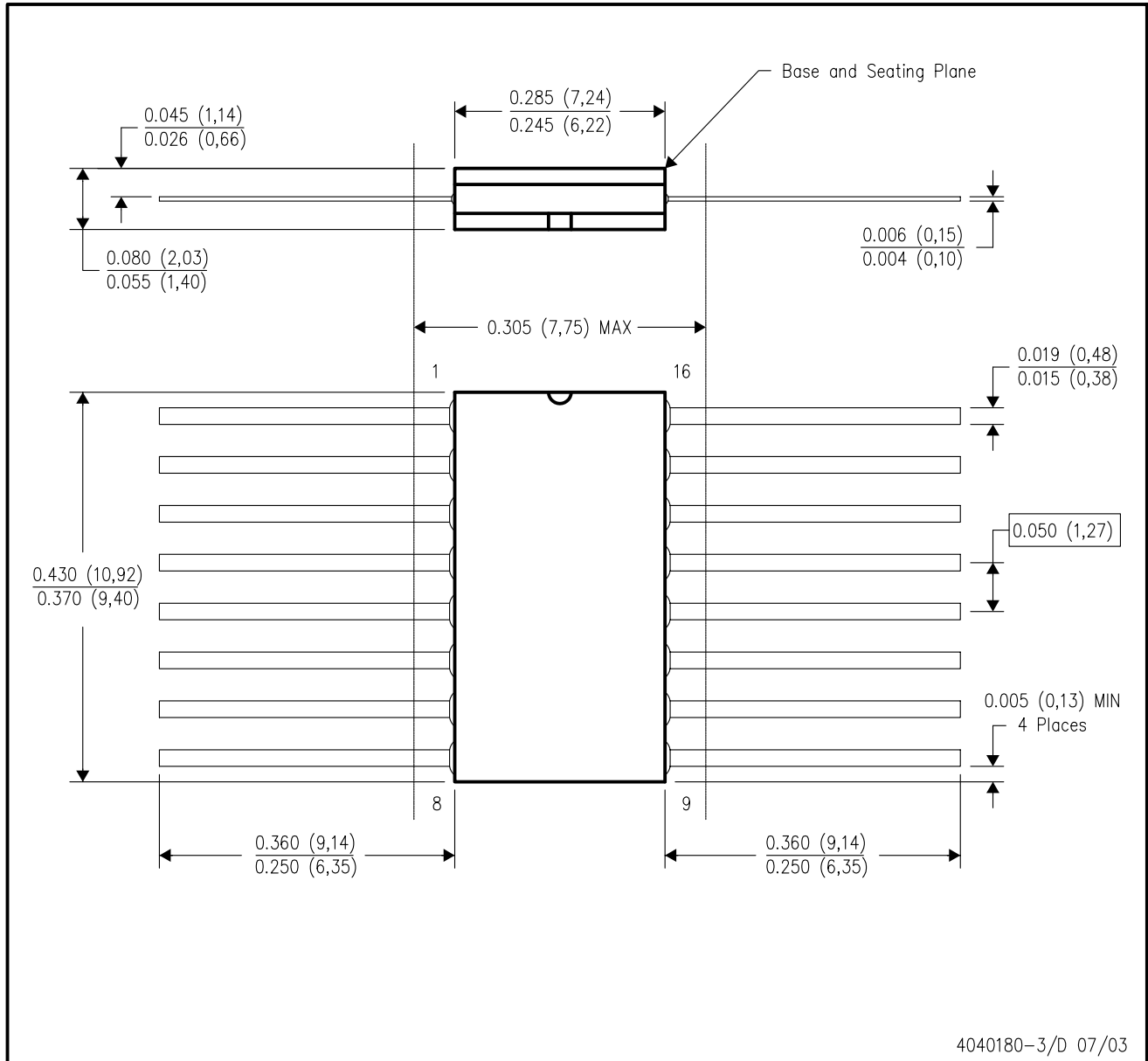
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

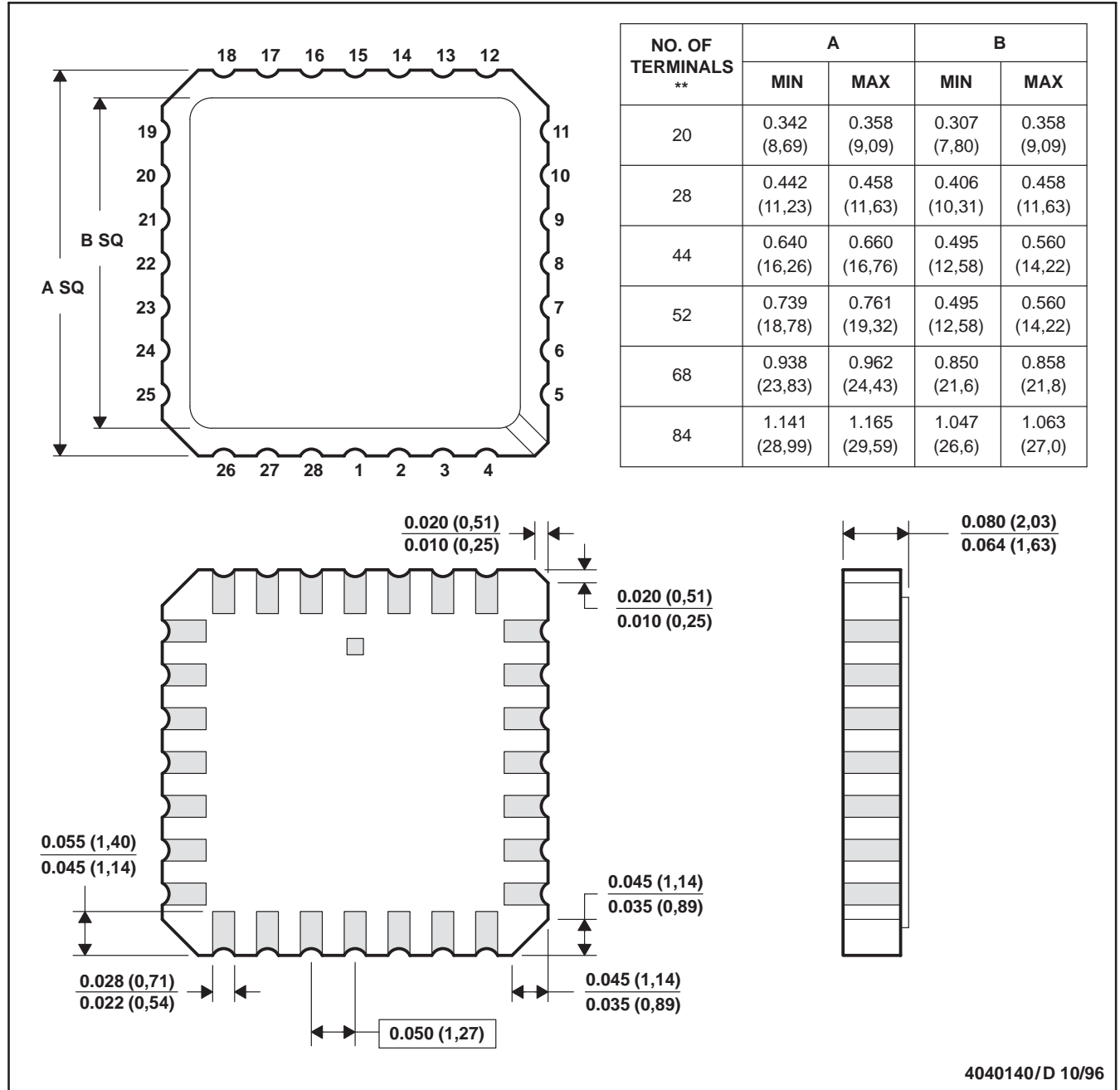
MECHANICAL DATA

MLCC006B – OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

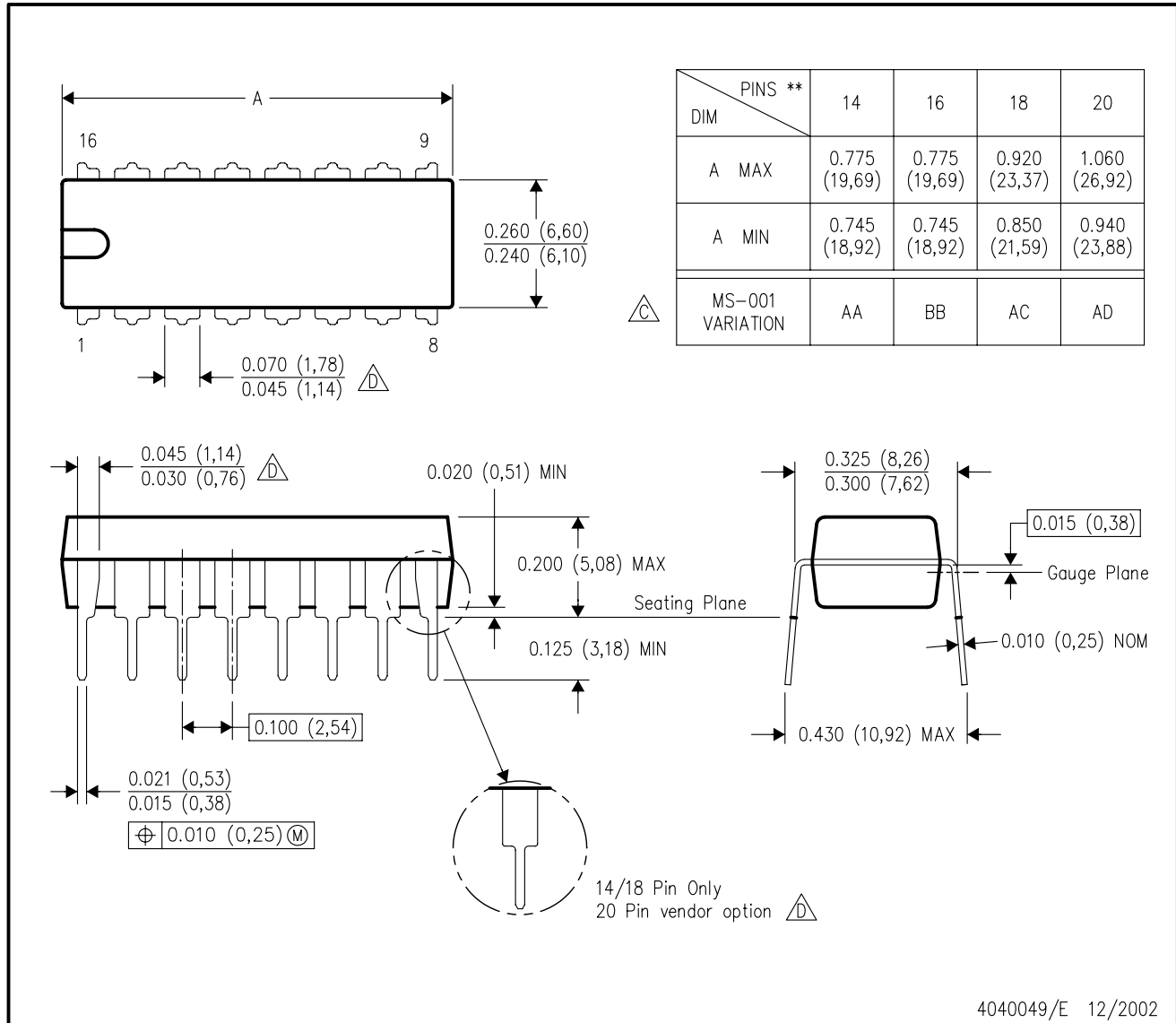
4040140/D 10/96

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



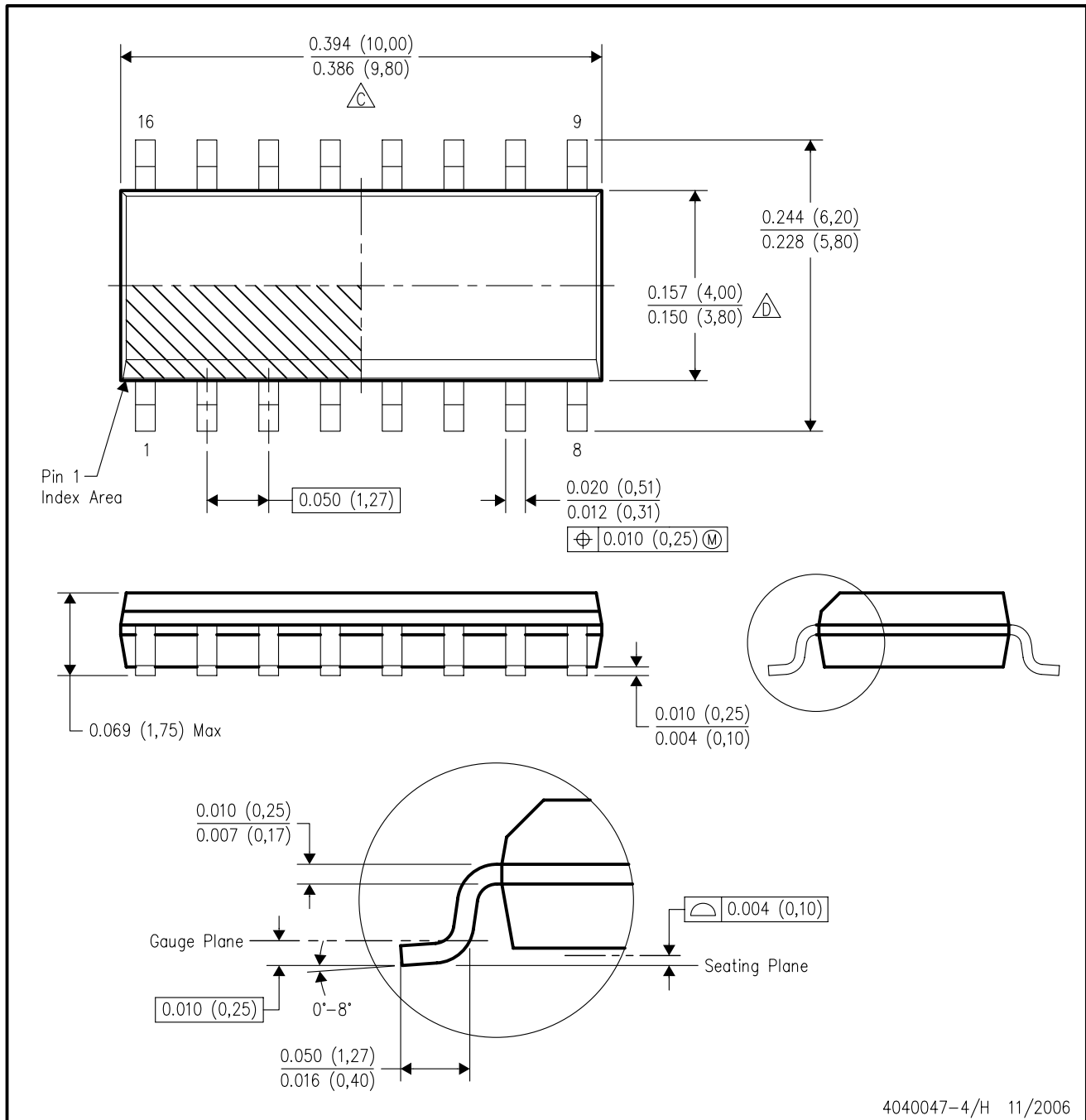
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

MECHANICAL DATA

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

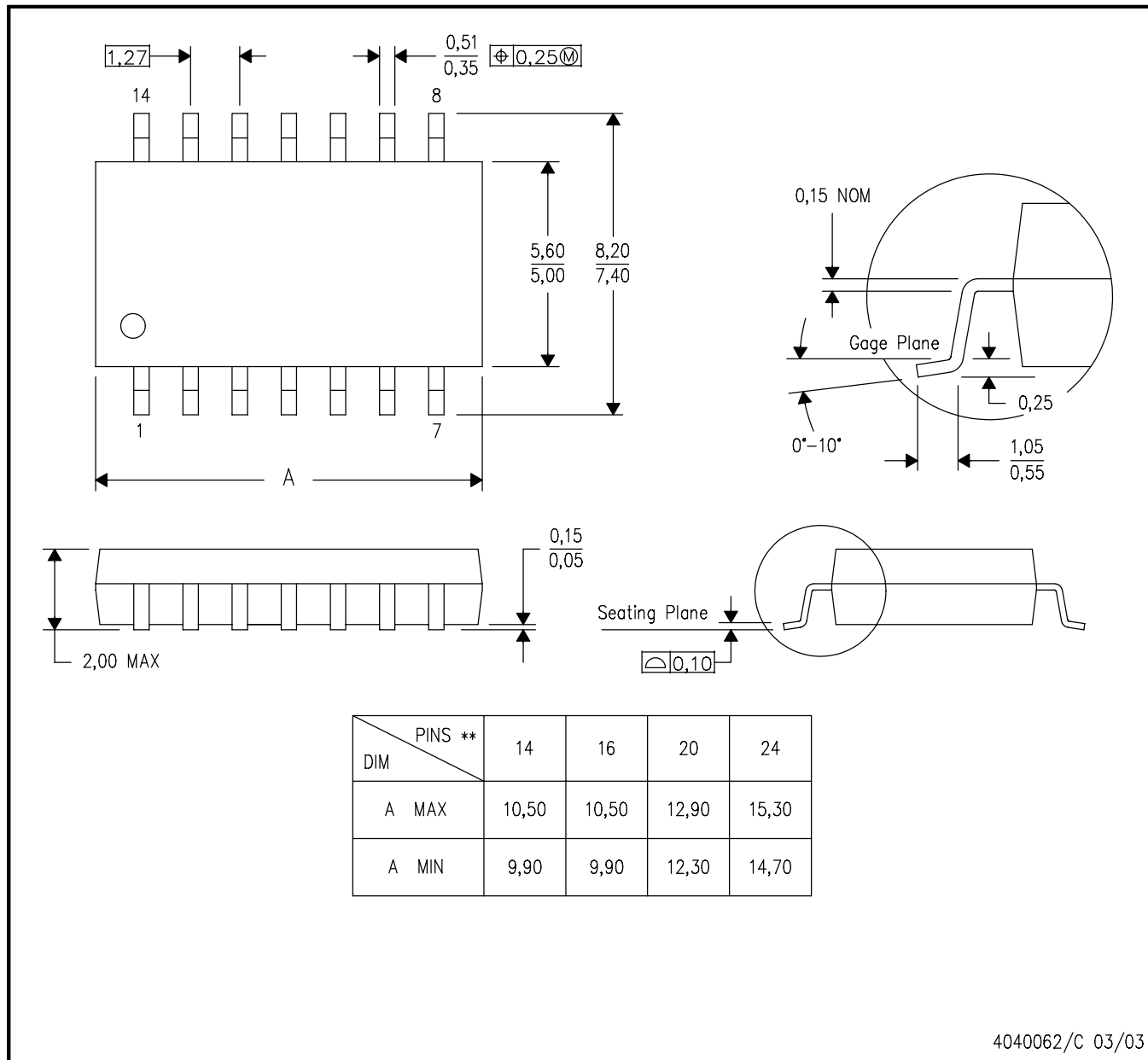
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

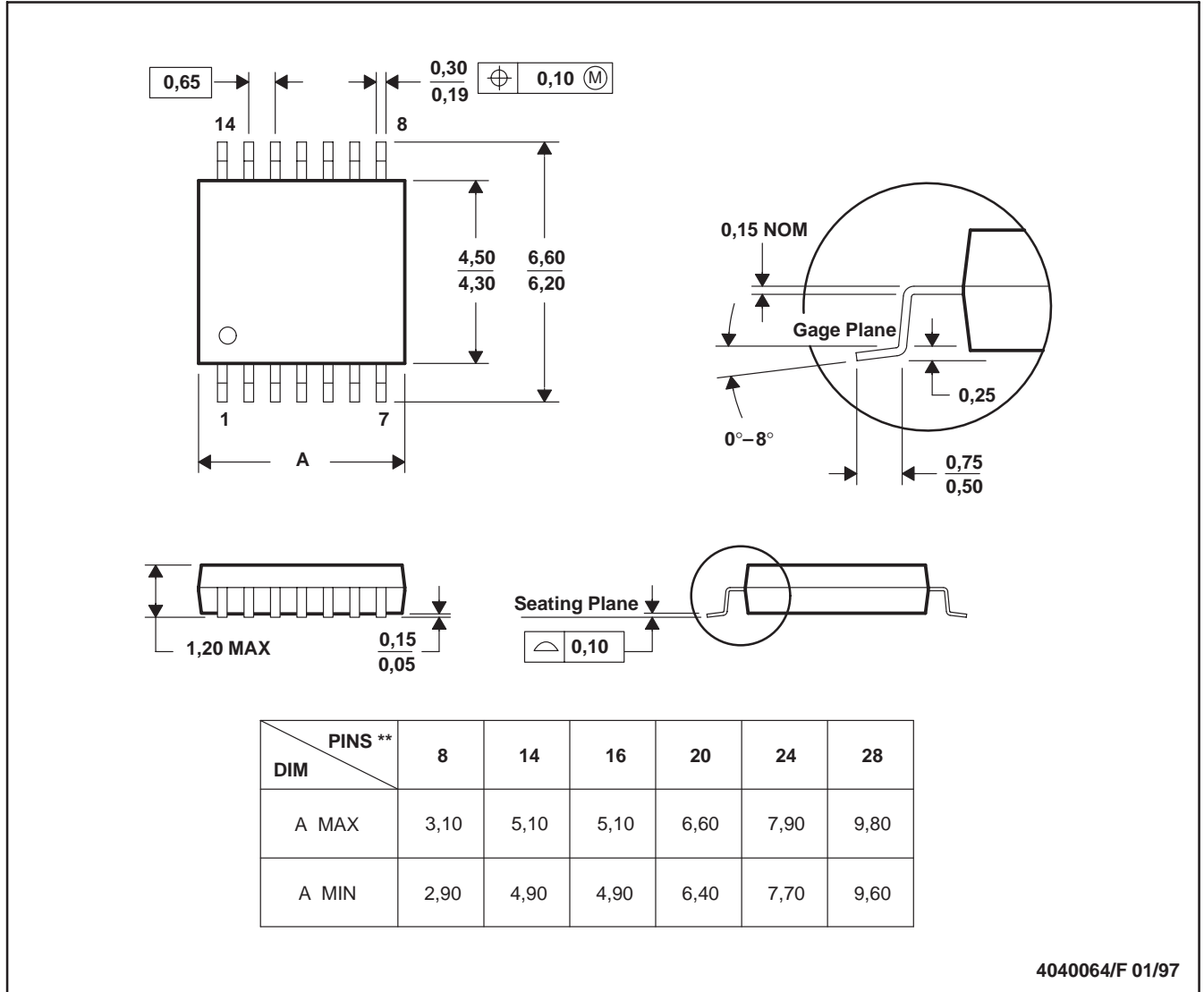
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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